

Datasheet revision 1.2

www.chipquik.com

## Solder Wire Sn96.5/Ag3.5 No-Clean with 2.0% Flux Core 0.3oz Tube

Product Highlights No-Clean Synthetic Flux Core The clear, non-corrosive, non-conductive residue is meant to be left on the board. 2.0% flux core Halogen content: None RoHS 3 and REACH compliant

**Specifications** 

Alloy: Wire Diameter: Flux Type: Flux Classification: Melting Point: Packaging: Shelf Life: Sn96.5/Ag3.5 0.020" (0.5mm) No-Clean Synthetic ROL0 221°C (430°F) 0.3oz Tube >60 months



## **Test Results**

| Test J-STD-004 or other requirements as stated            | Test Requirement                                      | Result   |
|---|---|--|
| Copper Mirror   | IPC-TM-650: 2.3.32                                    | L: No breakthrough   |
| Corrosion   | IPC-TM-650: 2.6.15                                    | L: No corrosion  |
| Quantitative Halides                                      | IPC-TM-650: 2.3.28.1                                  | L: <0.05%  |
| Electrochemical Migration                                 | IPC-TM-650: 2.6.14.1                                  | L: <1 decade drop (No-clean)   |
| Surface Insulation Resistance 85°C,<br>85% RH @ 168 Hours | IPC-TM-650: 2.6.3.7                                   | L: ≥100MΩ (No-clean)   |
| Visual  | IPC-TM-650: 3.4.2.5                                   | Clear and free from precipitation  |
| Conflict Minerals Compliance                              | Electronic Industry Citizenship<br>Coalition (EICC)   | Compliant  |
| REACH Compliance  | Articles 33 and 67 of Regulation (EC)<br>No 1907/2006 | Contains no substance >0.1% w/w that<br>is listed as a SVHC or restricted for<br>use in solder materials |

Conforms to the following Industry Standards:J-STD-004B, Amendment 1 (Solder Fluxes):YesJ-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):YesRoHS 3 Directive (EU) 2015/863:Yes